



Product Change Notification / MFOL-12SBEE528

Date:

20-Jan-2023

Product Category:

PON ONU/OLT Devices, SAS Silicon & SW

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5284 Final Notice: Qualification of GX92 as a new substrate material for PM8005C-F3EI, PM8004C-F3EI, XYRPM8005C-F3EI, XYRPM8004C-F3EI, and PAS5211A-F3EI catalog part numbers (CPN) available in 592L BGA (27x27x2.24mm) and 896L BGA (31x31x2.24mm) packages assembled at STAK assembly site.

Affected CPNs:

[MFOL-12SBEE528_Affected_CPN_01202023.pdf](#)

[MFOL-12SBEE528_Affected_CPN_01202023.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of GX92 as a new substrate material for PM8005C-F3EI, PM8004C-F3EI, XYRPM8005C-F3EI, XYRPM8004C-F3EI, and PAS5211A-F3EI catalog part numbers (CPN) available in 592L BGA (27x27x2.24mm) and 896L BGA (31x31x2.24mm) packages assembled at STAK assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	STATS CHIPPAC KOREA LTD. (STAK)	STATS CHIPPAC KOREA LTD. (STAK)
Die Attach Material	WF6317	WF6317
Underfill material	U8410-73C	U8410-73C
Solder Ball	SAC305	SAC305
Substrate Material	GX3	GX92

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying GX92 as a new substrate material.

Change Implementation Status:In Progress

Estimated First Ship Date:November 20, 2022 (date code: 2248)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	October 2022					November 2022			
Workweek	41	42	43	44	45	46	47	48	49
Qual Report Availability				X					
Final PCN Issue Date				X					
Estimated Implementation Date								X	

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:October 28, 2022: Issued final notification.

January 20, 2023: Re-issued final notification. Updated Notification subject, Description of change, Qual title and purpose to remove PM5369-FEI from affected CPN, as this part is not affected by this change.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the

material content of the applicable products.

Attachments:

[PCN_MFOL-12SBEE528_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PM8005C-F3EI

PM8004C-F3EI

XYRPM8005C-F3EI

XYRPM8004C-F3EI

PAS5211A-F3EI